

E1SPA15-25.00187M TR

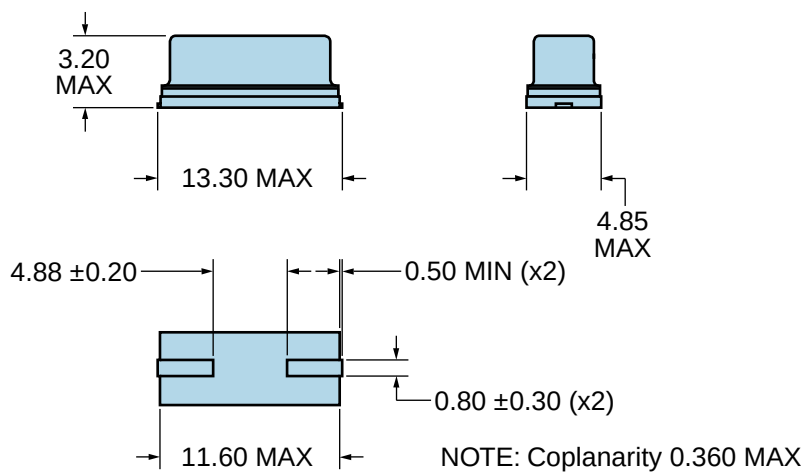


ELECTRICAL SPECIFICATIONS

Nominal Frequency	25.00187MHz
Frequency Tolerance/Stability	±10ppm at 25°C, ±15ppm over -20°C to +70°C
Aging at 25°C	±5ppm/year Maximum
Load Capacitance	15pF Parallel Resonant
Shunt Capacitance	7pF Maximum
Equivalent Series Resistance	40 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	1mWatt Maximum
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

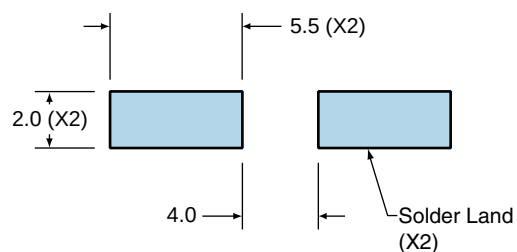
ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

E1SPA15-25.00187M TR **MECHANICAL DIMENSIONS (all dimensions in millimeters)**

LINE	MARKING
1	E25.001M E=Ecliptek Designator

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

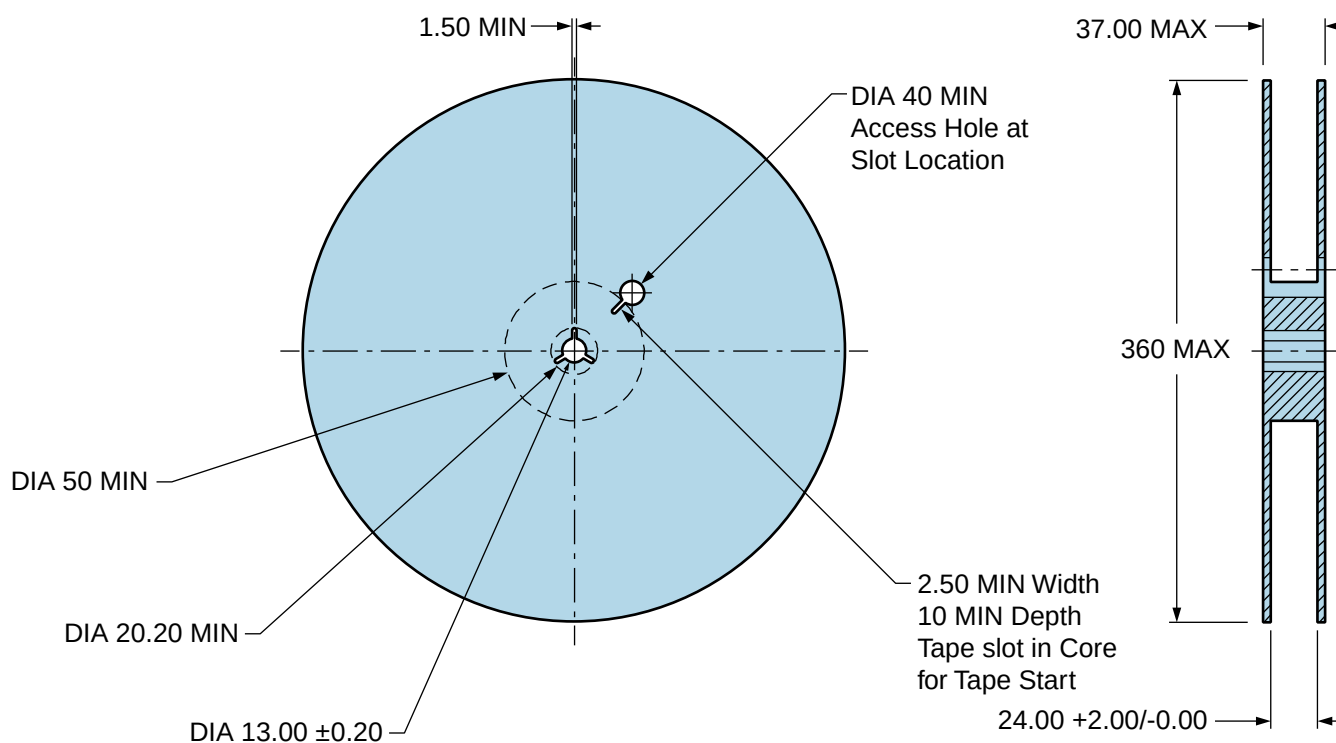
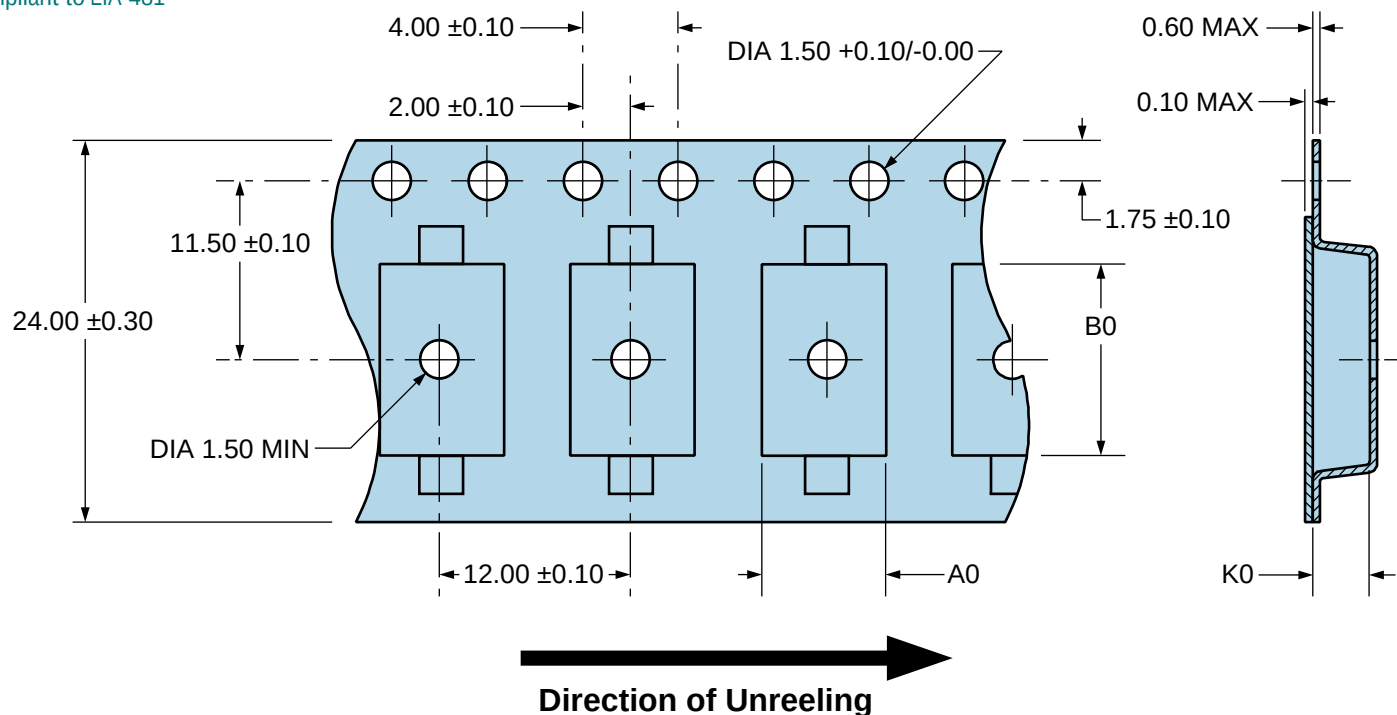
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Tape & Reel Dimensions

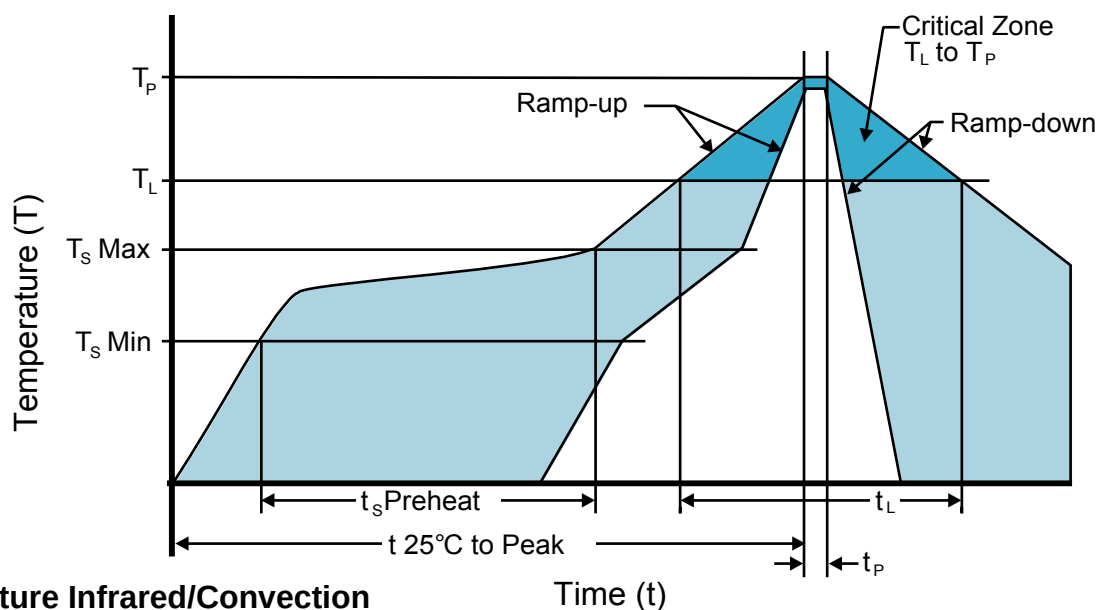
Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T_s MAX to T_L (Ramp-up Rate)	3°C/Second Maximum
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Preheat

- Temperature Minimum (T_s MIN)	150°C
- Temperature Typical (T_s TYP)	175°C
- Temperature Maximum (T_s MAX)	200°C
- Time (t_s MIN)	60 - 180 Seconds

Ramp-up Rate (T_L to T_P)	3°C/Second Maximum
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Time Maintained Above:

- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds

Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature (T_P Target)	250°C +0/-5°C
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Time within 5°C of actual peak (t_P)	20 - 40 Seconds
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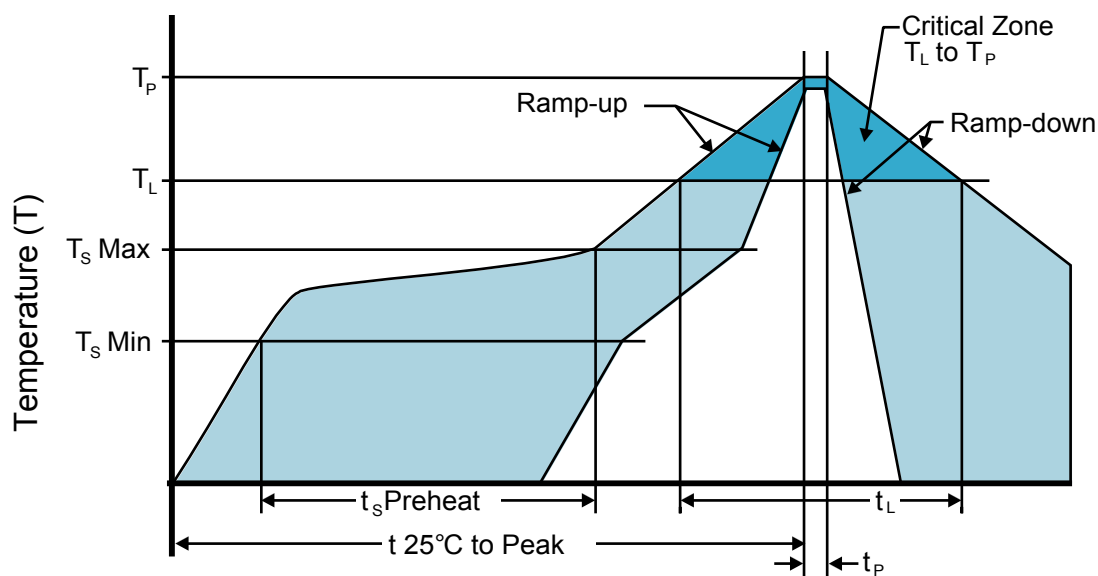
Ramp-down Rate	6°C/Second Maximum
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Time 25°C to Peak Temperature (t)	8 Minutes Maximum
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Moisture Sensitivity Level	Level 1
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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C Time (t)

Ts MAX to Tl (Ramp-up Rate) 5°C/Second Maximum

Preheat

- Temperature Minimum (Ts MIN) N/A
- Temperature Typical (Ts TYP) 150°C
- Temperature Maximum (Ts MAX) N/A
- Time (ts MIN) 30 - 60 Seconds

Ramp-up Rate (Tl to Tp) 5°C/Second Maximum

Time Maintained Above:

- Temperature (Tl) 150°C
- Time (tL) 200 Seconds Maximum

Peak Temperature (Tp) 245°C Maximum

Target Peak Temperature (Tp Target) 245°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (tp) 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

Ramp-down Rate 5°C/Second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.